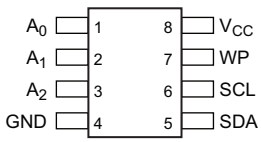
1. Pin Configurations and Pinouts

Table 1-1. Pin Configuration

Pin	Function
A_0	Address Input
A_1	Address Input
A_2	Address Input
GND	Ground
SDA	Serial Data
SCL	Serial Clock Input
WP	Write Protect
V_{CC}	Device Power Supply

Note: 1. For use of the 4-ball, 5-ball, and 6-ball WLCSP packages, please refer to Section 7. Device Addressing on page 9 for details about setting the A2, A1, and A0 hardware address bits.

8-lead SOIC

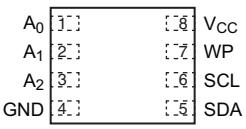


Top View

8-lead TSSOP

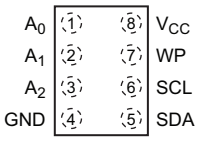
Top View

8-pad UDFN/XDFN



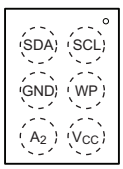
Top View

8-ball VFBGA



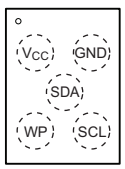
Top View

6-ball WLCSP [1]



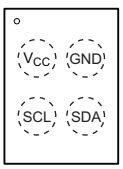
Top View

5-ball WLCSP [1]



Top View

4-ball WLCSP [1]



Top View

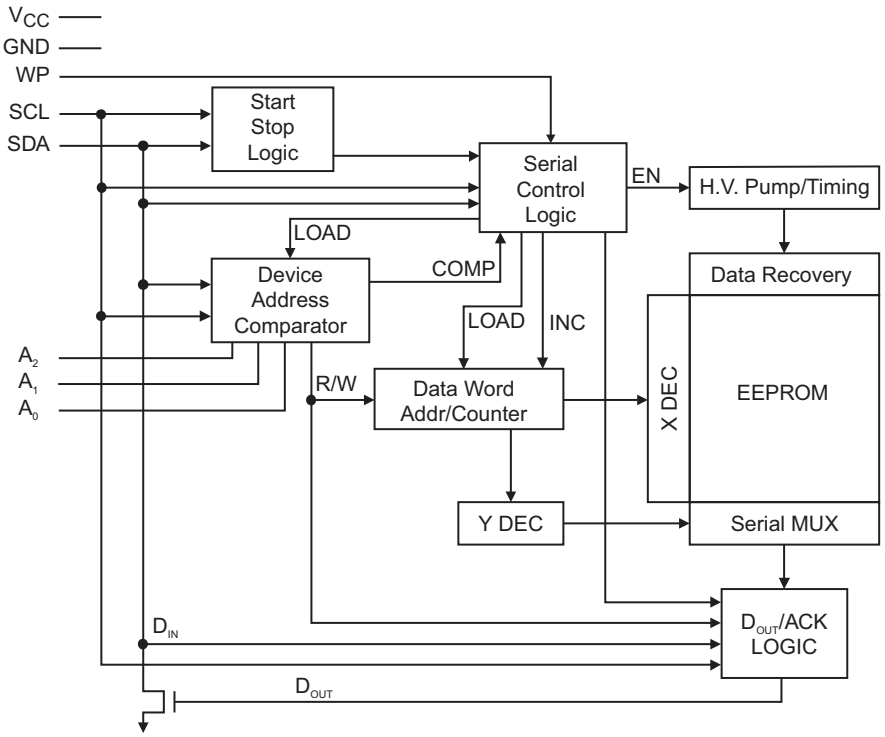
Note: Drawings are not to scale

2. Absolute Maximum Ratings*

Operating Temperature	-55°C to +125°C
Storage Temperature	-65°C to + 150°C
Voltage on any pin with respect to ground	-1.0 V +7.0V
Maximum Operating Voltage	6.25V
DC Output Current	5.0mA

*Notice: Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

3. Block Diagram



4. Pin Descriptions

Serial Clock (SCL): The SCL input is used to positive-edge clock data into each EEPROM device and negative-edge clock data out of each device.

Serial Data (SDA): The SDA pin is bidirectional for serial data transfer. This pin is open drain driven and may be wire-ORed with any number of other open-drain or open-collector devices.

Device Addresses (A_2, A_1, A_0): The A_2, A_1, and A_0 pins are device address inputs that are hard wired (directly to GND or to V_{CC}) for compatibility with other Atmel AT24C devices. When the pins are hard wired, as many as eight 64K devices may be addressed on a single bus system. (Device addressing is discussed in detail in Section 7., "Device Addressing" on page 9). A device is selected when a corresponding hardware and software match is true. If these pins are left floating, the A_2, A_1, and A_0 pins will be internally pulled down to GND. However, due to capacitive coupling that may appear during customer applications, Atmel recommends always connecting the address pins to a known state. When using a pull-up resistor, Atmel recommends using 10kΩ or less.

Write Protect (WP): The Write Protect input, when connected to GND, allows normal Write operations. When WP is connected directly to V_{CC}, all Write operations to the memory are inhibited. If the pin is left floating, the WP pin will be internally pulled down to GND: however, due to capacitive coupling that may appear during customer applications, Atmel recommends always connecting the WP pins to a known state. When using a pull-up resistor, Atmel recommends using 10kΩ or less.

Table 4-1. Write Protect

WP Pin Status	Part of the Array Protected
At V_{CC}	Full Array
At GND	Normal Read/Write Operations

5. Memory Organization

AT24C64D, 64K Serial EEPROM: The 64K is internally organized as 256 pages of 32-bytes each. Random word addressing requires a 13-bit data word address.

5.1 Pin Capacitance

Table 5-1. Pin Capacitance[1]

Applicable over recommended operating range from: T_A = 25°C, f = 1.0MHz, V_{CC} = 5.5V.

Symbol	Test Condition	Max	Units	Conditions
$C_{I/O}$	Input/Output Capacitance (SDA)	8	pF	$V_{I/O}$ = 0V
C_{IN}	Input Capacitance (A_0, A_1, A_2, and SCL)	6	pF	V_{IN} = 0V

Note: 1. This parameter is characterized and is not 100% tested.

5.2 DC Characteristics

Table 5-2. DC Characteristics

Applicable over recommended operating range from: T_{AI} = -40°C to +85°C, V_{CC} = 1.7V to 5.5V (unless otherwise noted).

Symbol	Parameter	Test Condition		Min	Typ	Max	Units
V_{CC1}	Supply Voltage			1.7		5.5	V
I_{CC1}	Supply Current	V_{CC} = 5.0V	Read at 400kHz		0.4	1.0	mA
I_{CC2}	Supply Current	V_{CC} = 5.0V	Write at 400kHz		2.0	3.0	mA
I_{SB1}	Standby Current	V_{CC} = 1.7V	V_{IN} = V_{CC} or V_{SS}			1.0	µA
		V_{CC} = 5.0V				6.0	µA
I_{LI}	Input Leakage Current V_{CC} = 5.0V	V_{IN} = V_{CC} or V_{SS}			0.10	3.0	µA
I_{LO}	Output Leakage Current V_{CC} = 5.0V	V_{OUT} = V_{CC} or V_{SS}			0.05	3.0	µA
V_{IL}	Input Low Level[1]			-0.6		V_{CC} x 0.3	V
V_{IH}	Input High Level[1]			V_{CC} x 0.7		V_{CC} + 0.5	V
V_{OL1}	Output Low Level	V_{CC} = 1.7V	I_{OL} = 0.15mA			0.2	V
V_{OL2}	Output Low Level	V_{CC} = 3.0V	I_{OL} = 2.1mA			0.4	V

Note: 1. V_{IL} min and V_{IH} max are reference only and are not tested.

5.3 AC Characteristics

Table 5-3. AC Characteristics (Industrial Temperature)

Applicable over recommended operating range from: T_{AI} = -40°C to +85°C, V_{CC} = 1.7V to 5.5V, CL = 100pF *(unless otherwise noted)*. Test conditions are listed in Note 2.

Symbol	Parameter	1.7V		2.5V, 5.0V		Units
		Min	Max	Min	Max	
f_{SCL}	Clock Frequency, SCL		400		1000	kHz
t_{LOW}	Clock Pulse Width Low	1300		400		ns
t_{HIGH}	Clock Pulse Width High	600		400		ns
t_I	Noise Suppression Time(1)		100		50	ns
t_{AA}	Clock Low to Data Out Valid	50	900	50	550	ns
t_{BUF}	Time the bus must be free before a new transmission can start(1)	1300		500		ns
$t_{HD.STA}$	Start Hold Time	600		250		ns
$t_{SU.STA}$	Start Set-up Time	600		250		ns
$t_{HD.DAT}$	Data In Hold Time	0		0		ns
$t_{SU.DAT}$	Data In Set-up Time	100		100		ns
t_R	Inputs Rise Time(1)		300		300	ns
t_F	Inputs Fall Time(1)		300		100	ns
$t_{SU.STO}$	Stop Set-up Time	600		250		ns
t_{DH}	Data Out Hold Time	50		50		ns
t_{WR}	Write Cycle Time		5		5	ms
Endurance(1)	25°C, Page Mode, 3.3V	1,000,000				Write Cycles

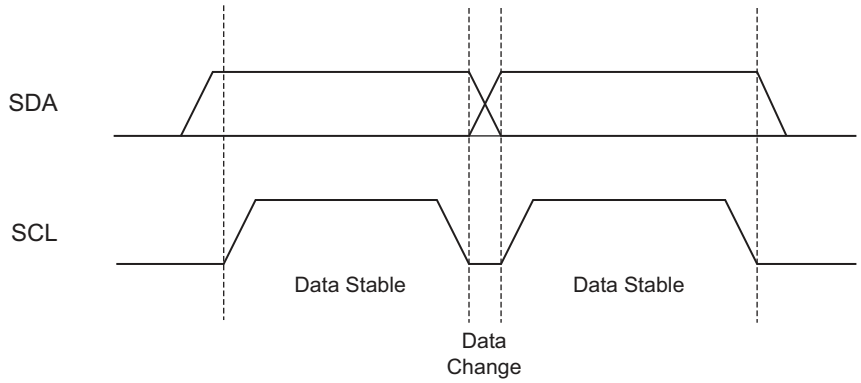
Notes: 1. This parameter is ensured by characterization and is not 100% tested.

2. AC measurement conditions:
   - R_L (connects to V_{CC}): 1.3kΩ (2.5V, 5.5V), 10kΩ (1.7V)
   - Input pulse voltages: $0.3V_{CC}$ to $0.7V_{CC}$
   - Input rise and fall times: ≤ 50ns
   - Input and output timing reference voltages: 0.5 x V_{CC}

6. Device Operation

Clock and Data Transitions: The SDA pin is normally pulled high with an external device. Data on the SDA pin may change only during SCL low time periods. Data changes during SCL high periods will indicate a start or stop condition as defined below.

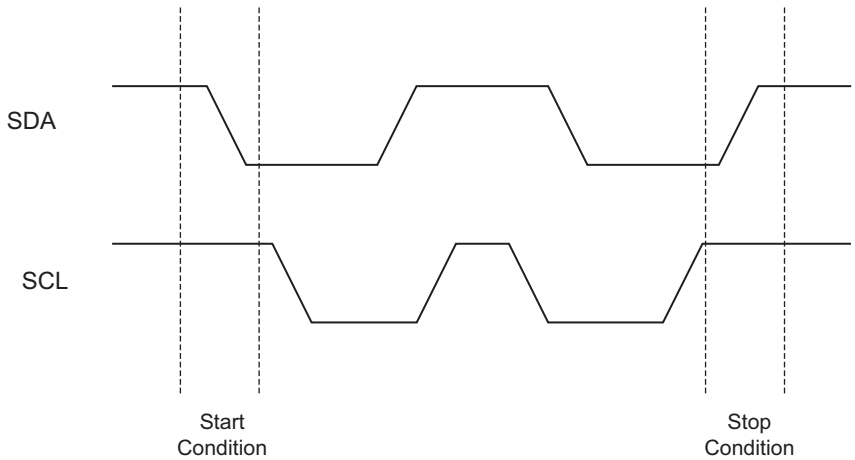
Figure 6-1. Data Validity



Start Condition: A high-to-low transition of SDA with SCL high is a Start condition that must precede every command.

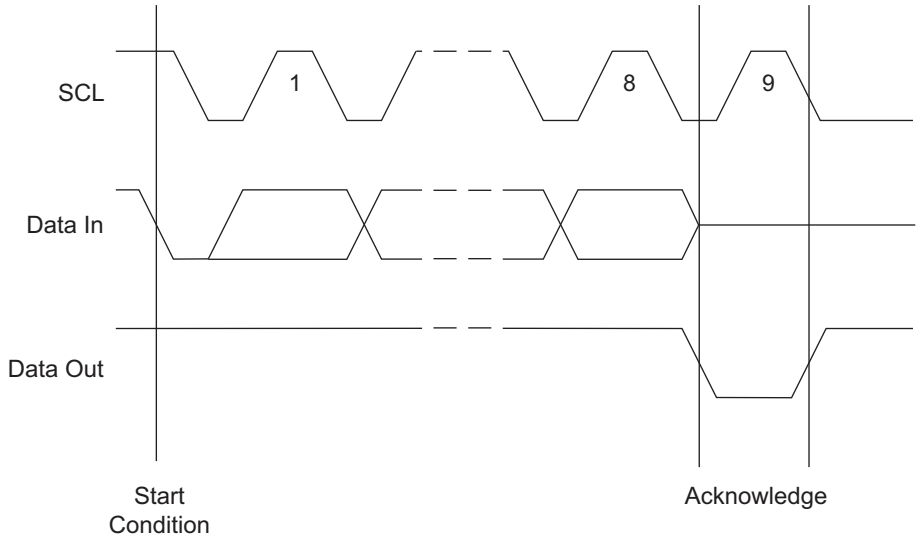
Stop Condition: A low-to-high transition of SDA with SCL high is a Stop condition. After a Read sequence, the Stop Condition will place the EEPROM in a standby power mode.

Figure 6-2. Start and Stop Definition



Acknowledge: All addresses and data words are serially transmitted to and from the EEPROM in 8-bit words. The receiving device sends a zero during the ninth clock cycle to acknowledge that it has received each word. This zero response is referred to as an Acknowledge.

Figure 6-3. Output Acknowledge



Standby Mode: The AT24C64D features a low-power standby mode that is enabled upon power-up and after the receipt of the Stop condition and the completion of any internal operations.

Software Reset: After an interruption in protocol, power loss or system reset, any 2-wire part can be protocol reset by following these steps:

1. Create a Start condition (if possible).
2. Clock nine cycles.
3. Create another Start followed by Stop condition as shown below.

The device should be ready for the next communication after the above steps have been completed. In the event that the device is still non-responsive or remains active on the SDA bus, a power cycle must be used to reset the device.

Figure 6-4. Software Reset

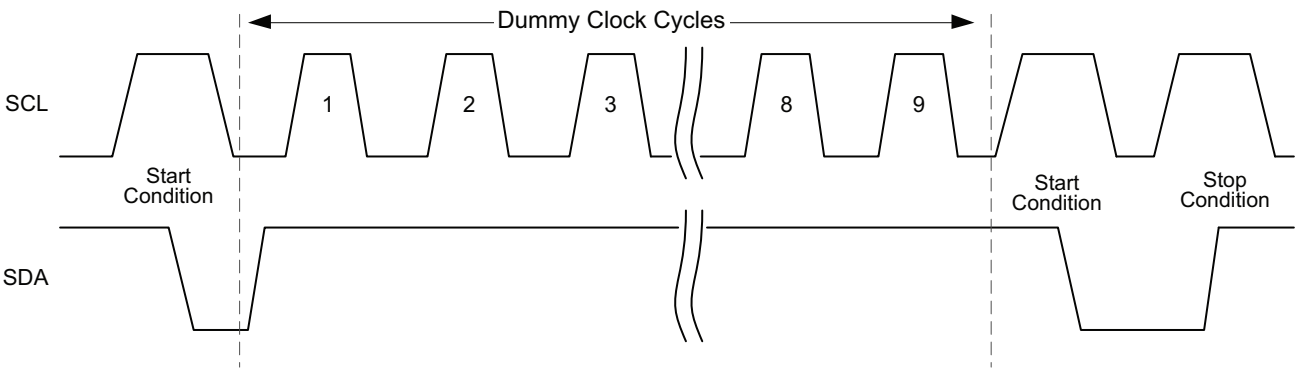


Figure 6-5. Bus Timing

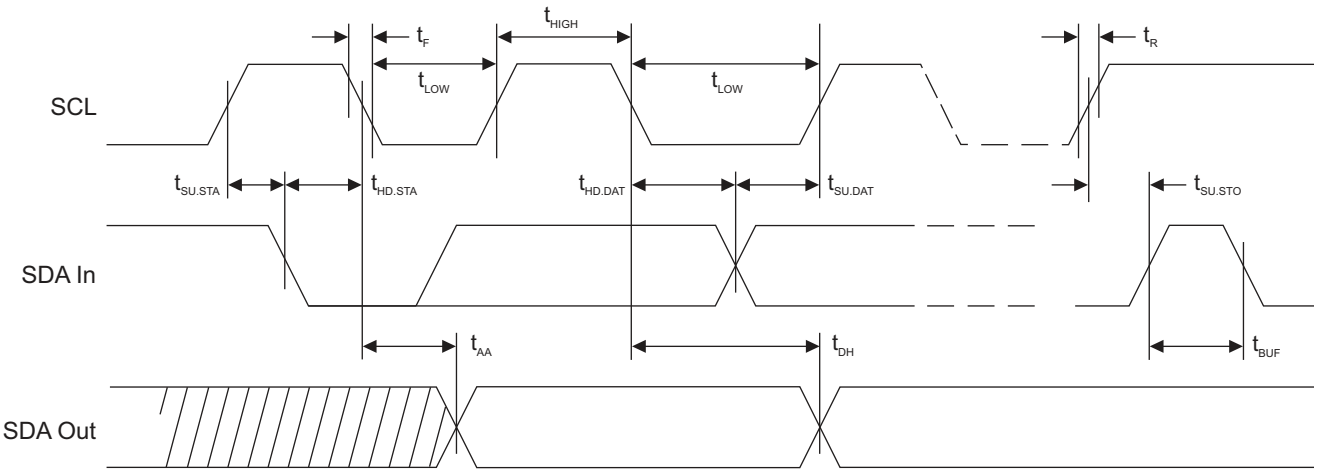
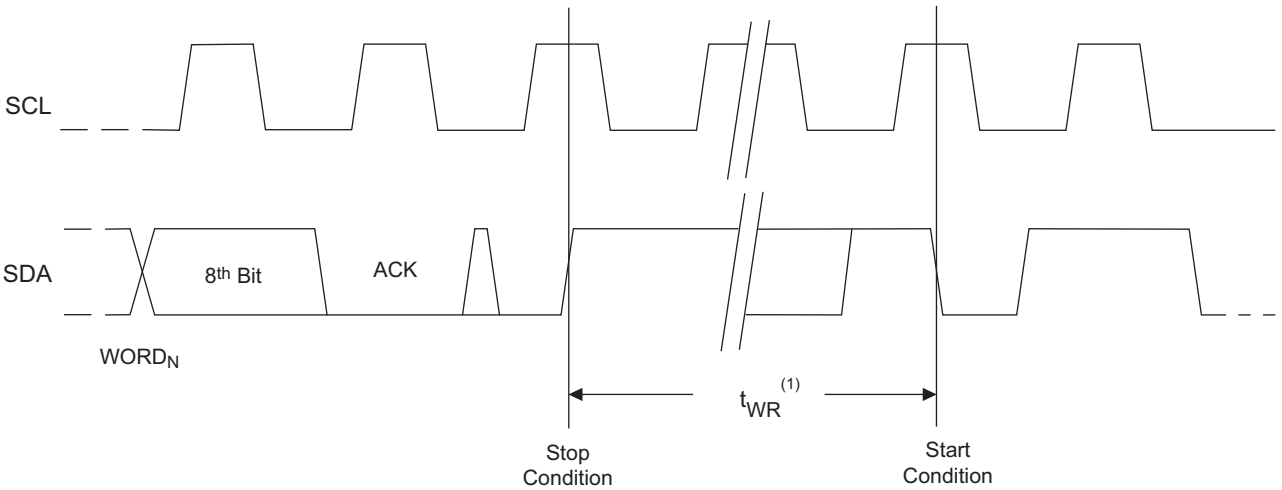


Figure 6-6. Write Cycle Timing



Note: 1. The write cycle time t_{WR} is the time from a valid stop condition of a write sequence to the end of the internal clear/write cycle.

7. Device Addressing

The 64K EEPROM requires an 8-bit device address word following a start condition to enable the chip for a read or write operation. The device address word consists of a mandatory '1010' sequence for the first four most significant bits (bit 7, bit 6, bit 5, and bit 4 as seen in Figure 7-1). This is common to all 2-wire Serial EEPROM devices.

The next three bits are the A2, A1, and A0 device address bits to allow as many as eight devices on the same bus. These bits must compare to their corresponding hard wired input pins, where applicable. The A_2, A_1, and A_0 pins use an internal proprietary circuit that pulls them to GND if the pins are allowed to float.

When utilizing the 6-ball WLCSP package, the A_1 and A_0 pins are not available and are internally pulled to ground; therefore, the A1 and A0 device address bits must always be set to a Logic 0 condition to communicate with the device. This condition is depicted in Figure 7-1 below.

When utilizing the 5-ball WLCSP package, the A_2, A_1 and A_0 pins are not available. The A_2 and A_1 pins are internally pulled to ground and thus the A2 and A1 device address bits must always be set to a Logic 0 condition to communicate with the device. The A_0 pin is internally connected to V_{CC} in this specific package only; therefore, the A0 software bit must be set to Logic 1 to communicate to the device. This condition is depicted in Figure 7-1 below.

When utilizing the 4-ball WLCSP package, the A_2, A_1, and A_0 pins are not available and are internally pulled to ground; therefore, the A2, A1 and A0 device address bits must always be set to a Logic 0 condition to communicate with the device. This condition is depicted in Figure 7-1 below.

The eighth bit of the device address is the Read/Write operation select bit. A read operation is initiated if this bit is high, and a Write operation is initiated if this bit is low.

Upon a compare of the device address, the EEPROM will output a zero. If a compare is not made, the device will return to a standby state.

Figure 7-1. Device Addressing

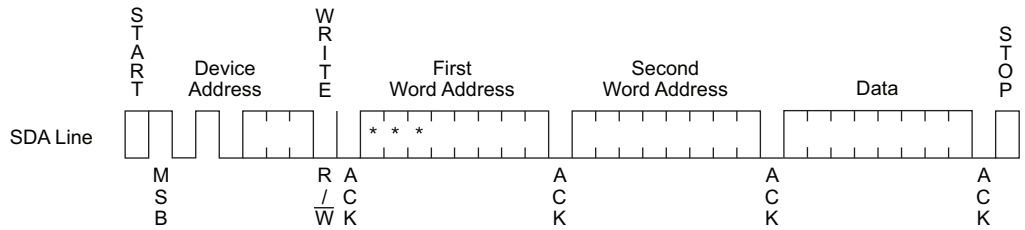
Package	Device Type Identifier				Hardware Address Bits			R/W Select
	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
SOIC, TSSOP, UDFN, XDFN, and VFBGA	1	0	1	0	A2	A1	A0	R/$\overline{W}$
6-ball WLCSP	1	0	1	0	A2	0	0	R/$\overline{W}$
5-ball WLCSP	1	0	1	0	0	0	1	R/$\overline{W}$
4-ball WLCSP	1	0	1	0	0	0	0	R/$\overline{W}$
	MSB							LSB

Data Security: AT24C64D has a hardware data protection scheme that allows the user to write protect the whole memory when the WP pin is at V_{CC}. The 4-ball WLCSP does not include a WP pin, and therefore no write protection is possible in this package only.

8. Write Operations

Byte Write: A Write operation requires two 8-bit data word addresses following the device address word and acknowledgment. Upon receipt of this address, the EEPROM will again respond with a zero, and then clock in the first 8-bit data word. Following receipt of the 8-bit data word, the EEPROM will output a zero. The addressing device, such as a microcontroller, must then terminate the Write sequence with a Stop condition. At this time, the EEPROM enters an internally-timed Write cycle, t_{WR}, to the nonvolatile memory (See Figure 6-6). All inputs are disabled during this Write cycle and the EEPROM will not respond until the Write is complete.

Figure 8-1. Byte Write

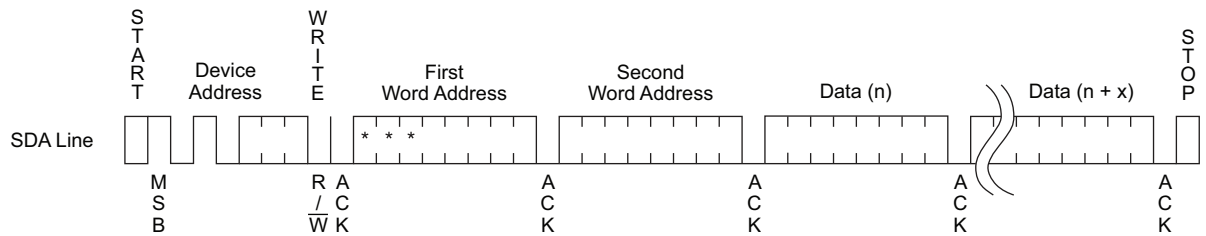


Note: * = Don't care bit.

Page Write: The 64K EEPROM is capable of 32-byte Page Writes.

A Page Write is initiated the same way as a Byte Write, but the microcontroller does not send a Stop condition after the first data word is clocked in. Instead, after the EEPROM acknowledges receipt of the first data word, the microcontroller can transmit up to 31 more data words. The EEPROM will respond with a zero after each data word received. The microcontroller must terminate the Page Write sequence with a Stop condition.

Figure 8-2. Page Write



Note: * = Don't care bit.

The data word address lower five bits are internally incremented following the receipt of each data word. The higher data word address bits are not incremented, retaining the memory page row location. When the word address, internally generated, reaches the page boundary, the following byte is placed at the beginning of the same page. If more than 32 data words are transmitted to the EEPROM, the data word address will roll-over and the previously loaded data will be altered. The address roll-over during Write is from the last byte of the current page to the first byte of the same page.

Acknowledge Polling: Once the internally-timed Write cycle has started and the EEPROM inputs are disabled, acknowledge polling can be initiated. This involves sending a Start condition followed by the device address word. The Read/Write bit is representative of the operation desired. Only if the internal Write cycle has completed will the EEPROM respond with a zero, allowing the Read or Write sequence to continue.

9. Read Operations

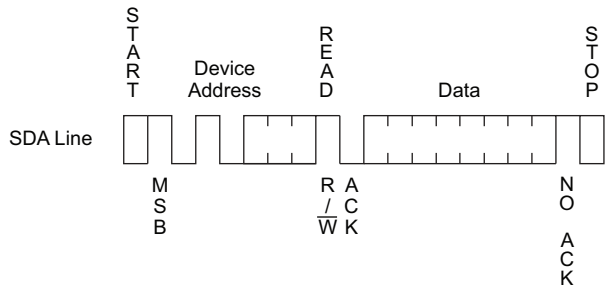
Read operations are initiated the same way as Write operations with the exception that the Read/Write select bit in the device address word is set to one. There are three Read operations:

- Current Address Read
- Random Address Read
- Sequential Read

Current Address Read: The internal data word address counter maintains the last address accessed during the last Read or Write operation, incremented by one. This address stays valid between operations as long as the chip power is maintained. The address roll-over during read is from the last byte of the last memory page, to the first byte of the first page.

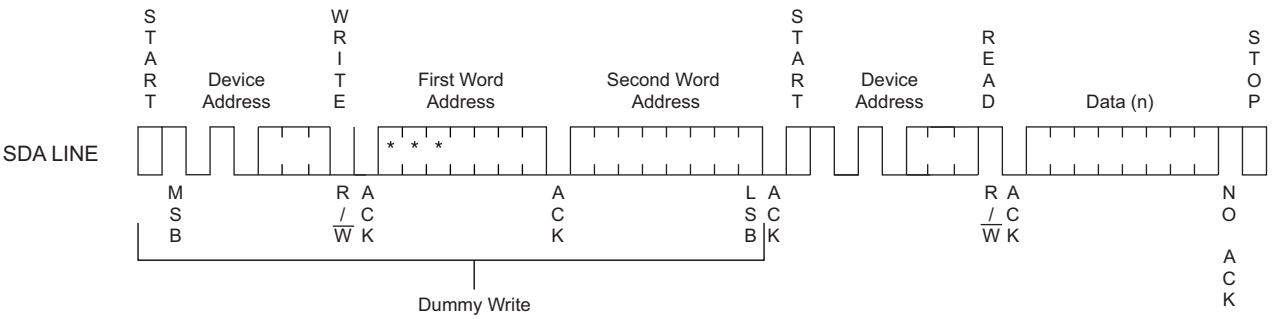
Once the device address with the Read/Write select bit set to one is clocked in and acknowledged by the EEPROM, the current address data word is serially clocked out. The microcontroller does not respond with an input zero but does generate a Stop condition.

Figure 9-1. Current Address Read



Random Read: A Random Read requires a dummy Byte Write sequence to load in the data word address. Once the device address word and data word address are clocked in and acknowledged by the EEPROM, the microcontroller must generate another Start condition. The microcontroller now initiates a Current Address Read by sending a device address with the Read/Write select bit high. The EEPROM acknowledges the device address and serially clocks out the data word. The microcontroller does not respond with a zero but does generate a Stop condition.

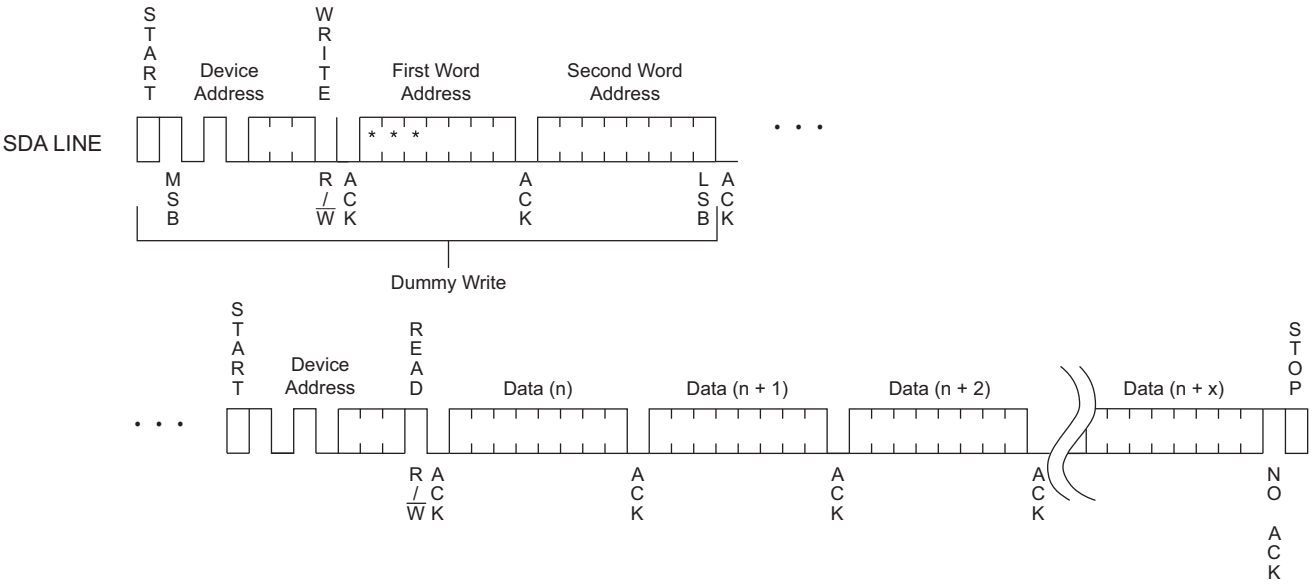
Figure 9-2. Random Read



Note: * = Don't care bit.

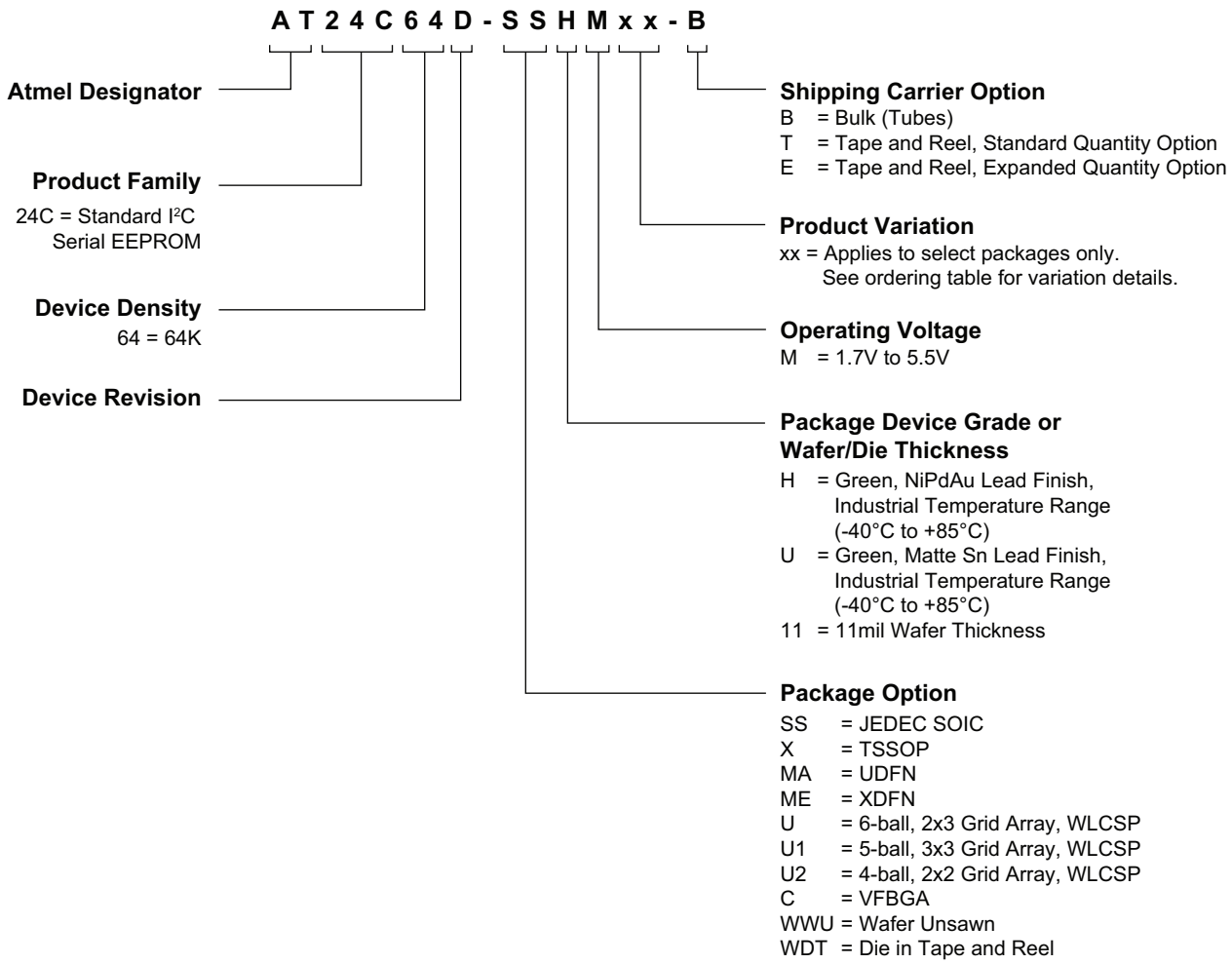
Sequential Read: Sequential Reads are initiated by either a Current Address Read or a Random Address Read. After the microcontroller receives a data word, it responds with an acknowledge. As long as the EEPROM receives an acknowledge, it will continue to increment the data word address and serially clock out sequential data words. When the memory address maximum address is reached, the data word address will roll-over and the Sequential Read will continue from the beginning of the array. The Sequential Read operation is terminated when the microcontroller does not respond with a zero but does generate a Stop condition.

Figure 9-3. Sequential Read



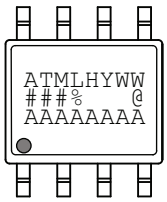
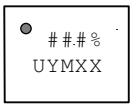
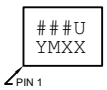
Note: * = Don't care bit.

10. Ordering Code Detail



11. Part Markings

AT24C64D: Package Marking Information

8-lead SOIC	8-lead TSSOP	8-pad XDFN
		1.8 x 2.2 mm Body 
8-pad UDFN	**4, 5, and 6-ball WLCSP**	**8-ball VFBGA**
2.0 x 3.0 mm Body 		1.5 x 2.0 mm Body 

Note 1: ● designates pin 1

Note 2: Package drawings are not to scale

Catalog Number Truncation			
AT24C64D		Truncation Code ###: 64D	
Date Codes			**Voltages**
Y = Year	M = Month	WW = Work Week of Assembly	% = Minimum Voltage
5: 2015 9: 2019 6: 2016 0: 2020 7: 2017 1: 2021 8: 2018 2: 2022	A: January B: February ... L: December	02: Week 2 04: Week 4 ... 52: Week 52	M: 1.7V min
Country of Assembly	**Lot Number**		**Grade/Lead Finish Material**
@ = Country of Assembly	AAA...A = Atmel Wafer Lot Number		U: Industrial/Matte Tin/SnAguCu H: Industrial/NiPdAu
Trace Code			**Atmel Truncation**
XX = Trace Code (Atmel Lot Numbers Correspond to Code) Example: AA, AB.... YZ, ZZ			AT: Atmel ATM: Atmel ATML: Atmel

4/27/2015

Atmel Package Mark Contact: DL-CSO-Assy_eng@atmel.com	**TITLE** **24C64DSM**, AT24C64D Package Marking Information	**DRAWING NO.** 24C64DSM	**REV.** E

12. Ordering Information

Atmel Ordering Code	Lead Finish	Package	Delivery Information		Operating Range
			Form	Quantity	
AT24C64D-SSHM-B	NiPdAu (Lead-free/Halogen-free)	8S1	Bulk (Tubes)	100 per Tube	Industrial Temperature (-40°C to 85°C)
AT24C64D-SSHM-T			Tape and Reel	4,000 per Reel	
AT24C64D-XHM-B		8X	Bulk (Tubes)	100 per Tube	
AT24C64D-XHM-T			Tape and Reel	4,000 per Reel	
AT24C64D-MAHM-T		8MA2	Tape and Reel	5,000 per Reel	
AT24C64D-MAHM-E			Tape and Reel	15,000 per Reel	
AT24C64D-MEHM-T		8ME1	Tape and Reel	5,000 per Reel	
AT24C64D-UUM0B-T(1)	SnAgCu (Lead-free/Halogen-free)	6U-2	Tape and Reel	5,000 per Reel	
AT24C64D-U1UM0B-T(1)		5U-4	Tape and Reel	5,000 per Reel	
AT24C64D-U2UM0B-T(1)		4U-12	Tape and Reel	5,000 per Reel	
AT24C64D-CUM-T		8U2-1	Tape and Reel	5,000 per Reel	
AT24C64D-WWU11M(2)	N/A	Wafer Sale	Note 2		

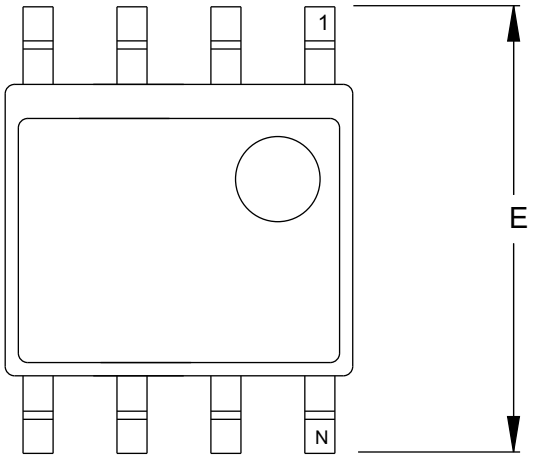
Notes: 1. WLCSP Package:
- This device includes a backside coating to increase product robustness.
- **CAUTION**: Exposure to ultraviolet (UV) light can degrade the data stored in the EEPROM cells. Therefore, customers who use a WLCSP product must ensure that exposure to ultraviolet light does ***not*** occur.

2. Contact Atmel Sales for Wafer sales.

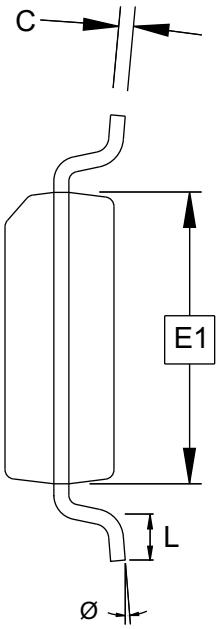
Package Type	
8S1	8-lead, 0.150” wide, Plastic Gull Wing Small Outline (JEDEC SOIC)
8X	8-lead, 4.40mm body, Plastic Thin Shrink Small Outline Package (TSSOP)
8MA2	8-pad, 2.00mm x 3.00mm body, 0.50mm pitch, Dual No Lead (UDFN)
8ME1	8-pad, 1.80mm x 2.20mm body, Extra Thin DFN (XDFN)
6U-2	6-ball, 2x3 Grid Array, Wafer Level Chip Scale Package (WLCSP)
5U-4	5-ball, 3x3 Grid Array, Wafer Level Chip Scale Package (WLCSP)
4U-12	4-ball, 2x2 Grid Array, Wafer Level Chip Scale Package (WLCSP)
8U2-1	8-ball, Die Ball Grid Array (VFBGA)

13. Packaging Information

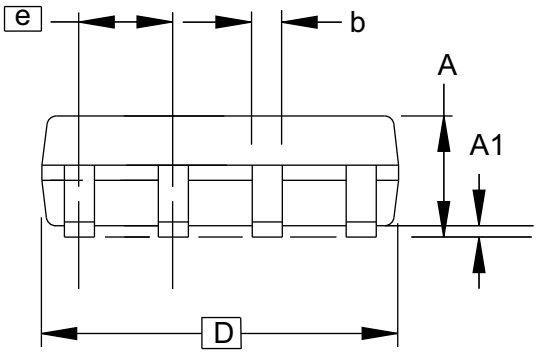
13.1 8S1 — 8-lead JEDEC SOIC



TOP VIEW



END VIEW



SIDE VIEW

Notes: This drawing is for general information only.
Refer to JEDEC Drawing MS-012, Variation AA
for proper dimensions, tolerances, datums, etc.

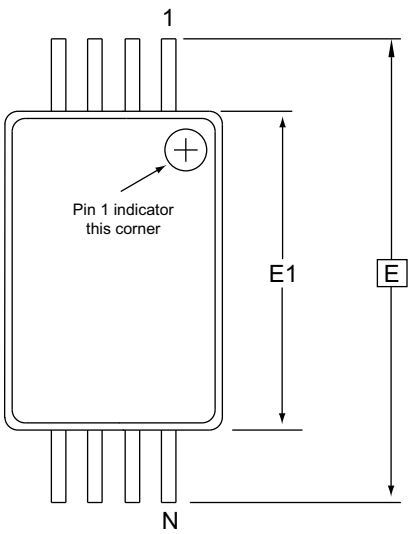
COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	1.75	
A1	0.10	–	0.25	
b	0.31	–	0.51	
C	0.17	–	0.25	
D		4.90 BSC		
E		6.00 BSC		
E1		3.90 BSC		
e		1.27 BSC		
L	0.40	–	1.27	
Ø	0°	–	8°	

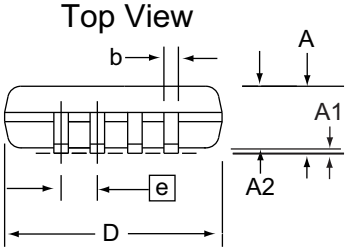
3/6/2015

Atmel Package Drawing Contact: packagedrawings@atmel.com	**TITLE** 8S1, 8-lead (0.150” Wide Body), Plastic Gull Wing Small Outline (JEDEC SOIC)	**GPC** SWB	**DRAWING NO.** 8S1	**REV.** H

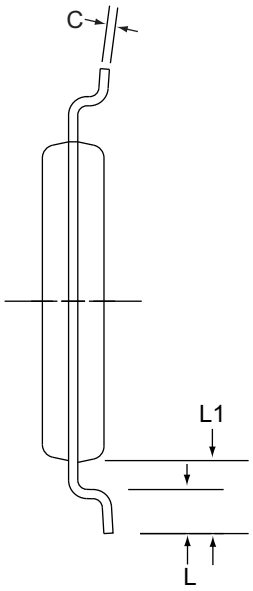
13.2 8X — 8-lead TSSOP



Top View



Side View



End View

Notes:
1. This drawing is for general information only. Refer to JEDEC Drawing MO-153, Variation AA, for proper dimensions, tolerances, datums, etc.
2. Dimension D does not include mold Flash, protrusions or gate burrs. Mold Flash, protrusions and gate burrs shall not exceed 0.15mm (0.006in) per side.
3. Dimension E1 does not include inter-lead Flash or protrusions. Inter-lead Flash and protrusions shall not exceed 0.25mm (0.010in) per side.
4. Dimension b does not include Dambar protrusion. Allowable Dambar protrusion shall be 0.08mm total in excess of the b dimension at maximum material condition. Dambar cannot be located on the lower radius of the foot. Minimum space between protrusion and adjacent lead is 0.07mm.
5. Dimension D and E1 to be determined at Datum Plane H.

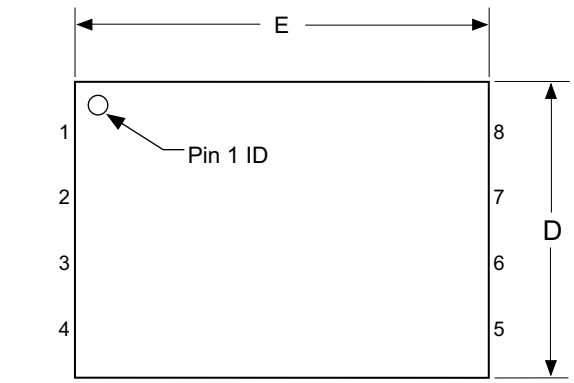
COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	-	-	1.20	
A1	0.05	-	0.15	
A2	0.80	1.00	1.05	
D	2.90	3.00	3.10	2, 5
E		6.40 BSC		
E1	4.30	4.40	4.50	3, 5
b	0.19	0.25	0.30	4
e		0.65 BSC		
L	0.45	0.60	0.75	
L1		1.00 REF		
C	0.09	-	0.20	

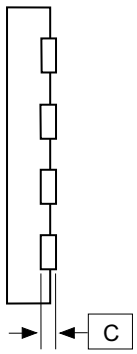
2/27/14

Atmel Package Drawing Contact: packagedrawings@atmel.com	TITLE 8X, 8-lead 4.4mm Body, Plastic Thin Shrink Small Outline Package (TSSOP)	GPC TNR	DRAWING NO. 8X	REV. E

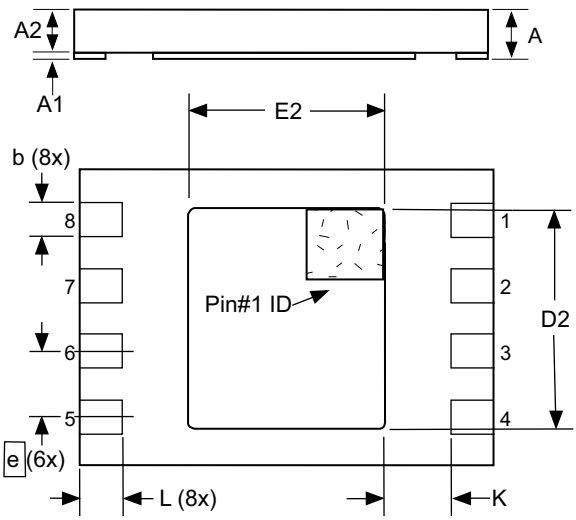
13.3 8MA2 — 8-pad UDFN



TOP VIEW



SIDE VIEW



BOTTOM VIEW

Notes:
1. This drawing is for general information only. Refer to Drawing MO-229, for proper dimensions, tolerances, datums, etc.
2. The Pin #1 ID is a laser-marked feature on Top View.
3. Dimensions b applies to metallized terminal and is measured between 0.15 mm and 0.30 mm from the terminal tip. If the terminal has the optional radius on the other end of the terminal, the dimension should not be measured in that radius area.
4. The Pin #1 ID on the Bottom View is an orientation feature on the thermal pad.

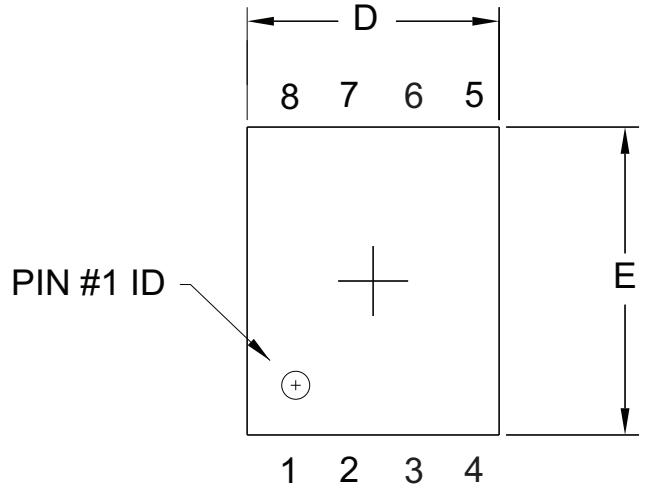
COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	0.50	0.55	0.60	
A1	0.0	0.02	0.05	
A2	-	-	0.55	
D	1.90	2.00	2.10	
D2	1.40	1.50	1.60	
E	2.90	3.00	3.10	
E2	1.20	1.30	1.40	
b	0.18	0.25	0.30	3
C	1.52 REF			
L	0.30	0.35	0.40	
e	0.50 BSC			
K	0.20	-	-	

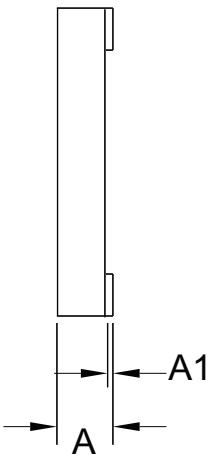
11/26/14

Atmel Package Drawing Contact: packagedrawings@atmel.com	TITLE 8MA2, 8-pad 2 x 3 x 0.6mm Body, Thermally Enhanced Plastic Ultra Thin Dual Flat No-Lead Package (UDFN)	GPC YNZ	DRAWING NO. 8MA2	REV. G

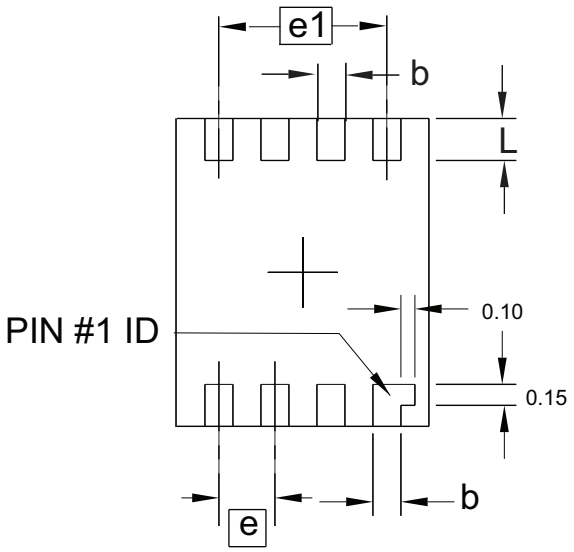
13.4 8ME1 — 8-pad XDFN



Top View



Side View



End View

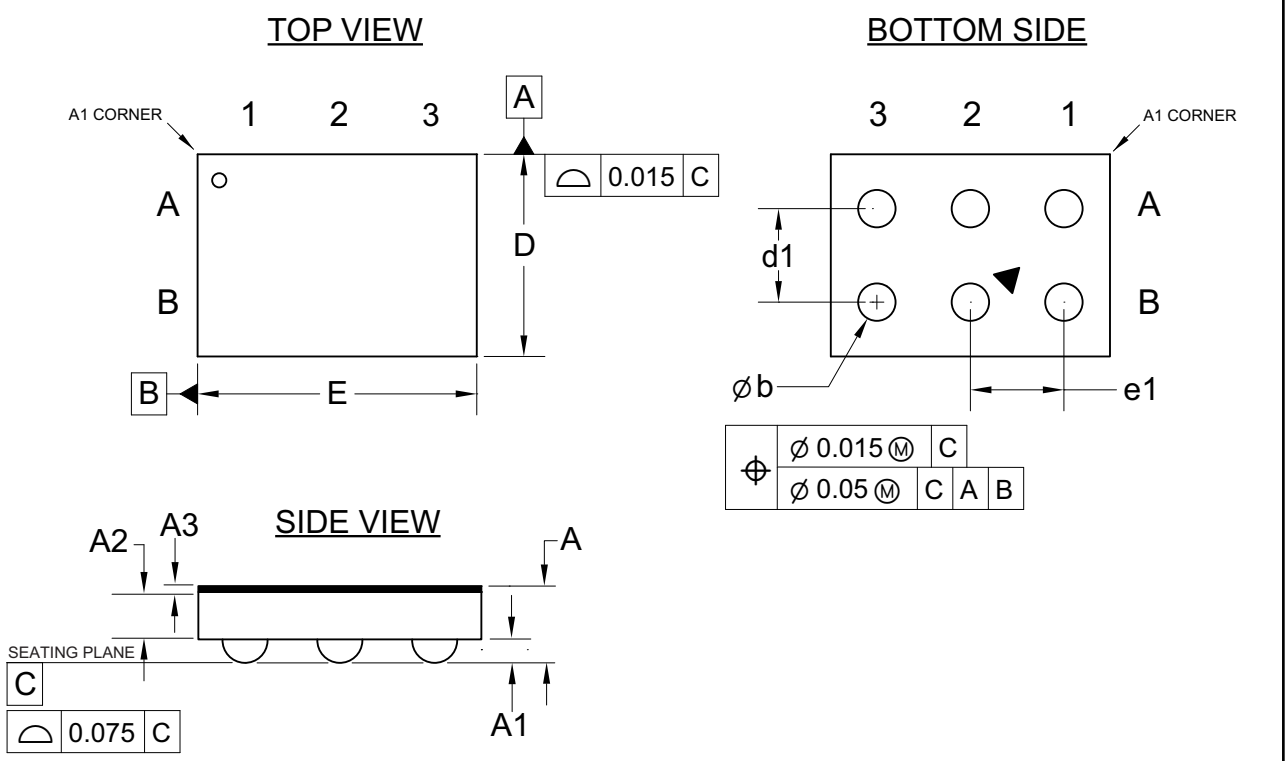
COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	0.40	
A1	0.00	–	0.05	
D	1.70	1.80	1.90	
E	2.10	2.20	2.30	
b	0.15	0.20	0.25	
e	0.40 TYP			
e1	1.20 REF			
L	0.26	0.30	0.35	

9/10/2012

Atmel Package Drawing Contact: packagedrawings@atmel.com	TITLE **8ME1**, 8-pad (1.80mm x 2.20mm body) Extra Thin DFN (XDFN)	GPC DTP	DRAWING NO. 8ME1	REV. B

13.5 6U-2 — 6-ball WLCSP



PIN ASSIGNMENT MATRIX

	1	2	3
A	SCL	WP	V_{CC}
B	SDA	GND	A_2

COMMON DIMENSIONS
(Unit of Measure = mm)

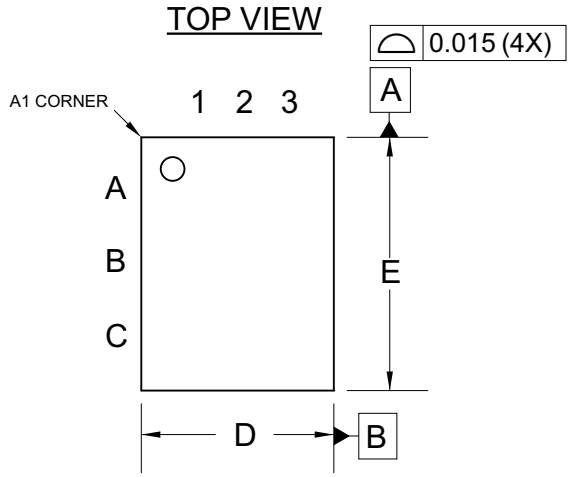
SYMBOL	MIN	TYP	MAX	NOTE
A	0.260	0.295	0.330	
A1	0.080	0.095	0.110	
A2	0.160	0.175	0.190	
A3	0.025 REF			3
D	Contact Atmel for details			
d1	0.40 BSC			
E	Contact Atmel for details			
e1	0.40 BSC			
b	0.170	0.185	0.200	

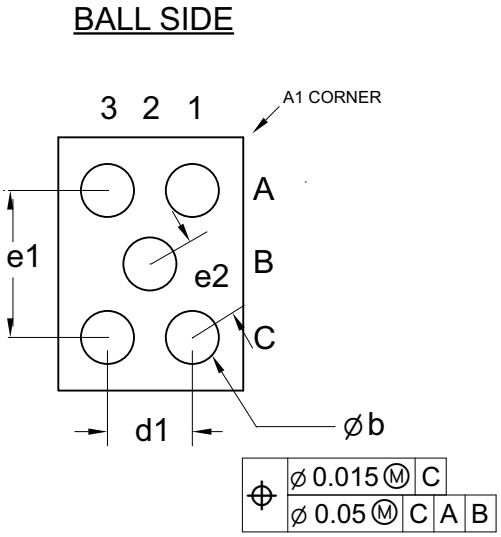
Note: 1. Dimensions are NOT to scale.
2. Solder ball composition is 95.5Sn-4.0Ag-0.5Cu.
3. Product offered with Back Side Coating (BSC)

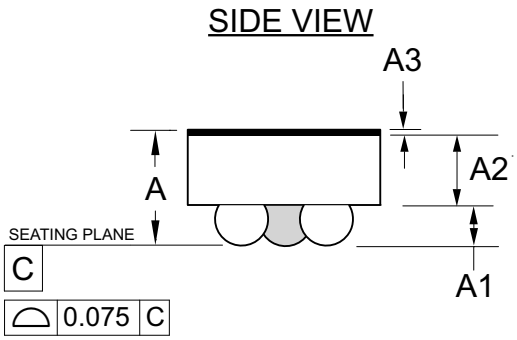
5/6/15

Atmel Package Drawing Contact: packagedrawings@atmel.com	TITLE 6U-2, 6-ball, 2x3 Array, 0.40mm pitch Wafer Level Chip Scale Package (WLCSP) with BSC	GPC GMK	DRAWING NO. 6U-2	REV. C

13.6 5U-4 — 5-ball WLCSP







PIN ASSIGNMENT MATRIX

	1	2	3
A	V_{CC}	n/a	GND
B	n/a	SDA	n/a
C	WP	n/a	SCL

COMMON DIMENSIONS
(Unit of Measure = mm)

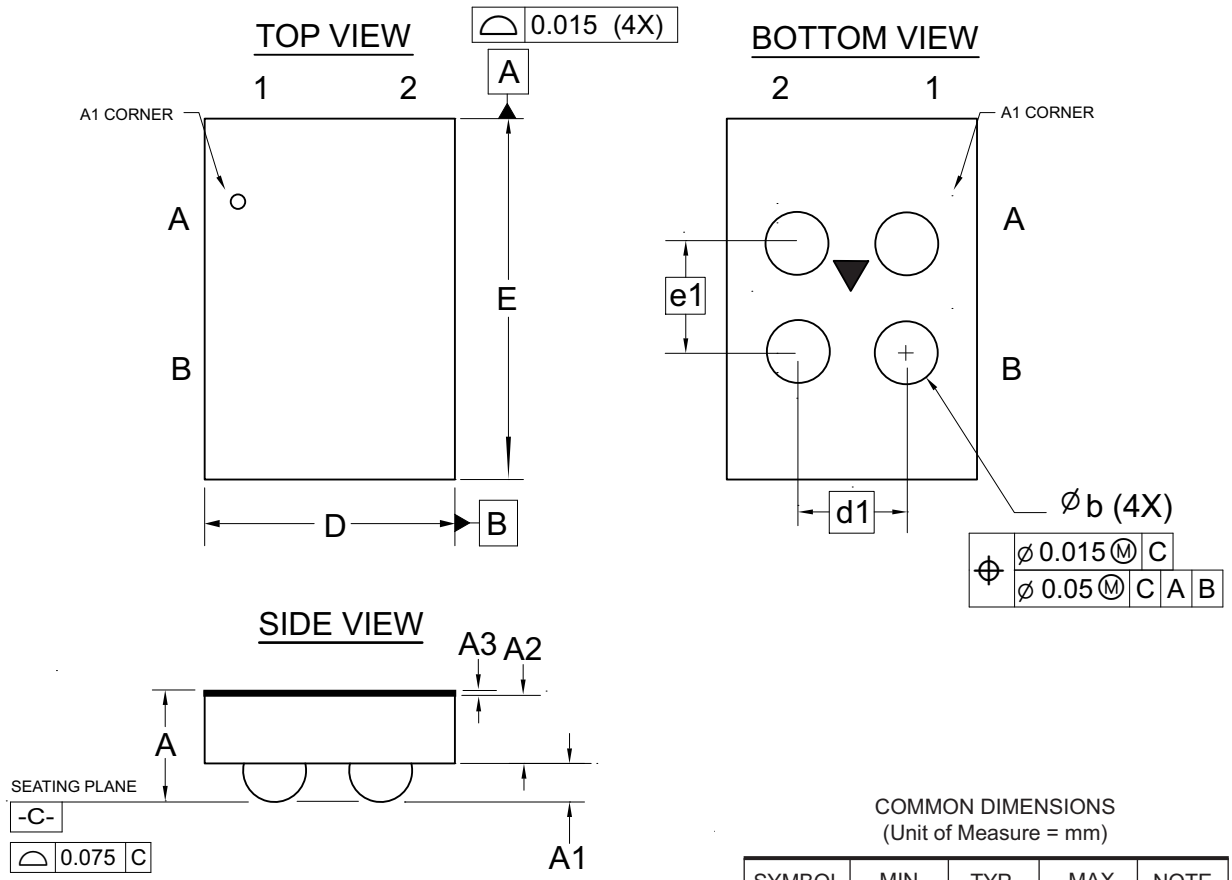
SYMBOL	MIN	TYP	MAX	NOTE
A	0.260	0.295	0.330	
A1	0.080	0.095	0.110	
A2	0.160	0.175	0.190	
A3	0.025 REF			3
D	Contact Atmel for details			
d1	0.400 BSC			
E	Contact Atmel for details			
e1	0.693 BSC			
e2	0.400 BSC			
b	0.170	0.185	0.200	

Note: 1. Dimensions are NOT to scale.
2. Solder ball composition is 95.5Sn-4.0Ag-0.5Cu.
3. Product offered with Back Side Coating (BSC)

5/6/15

Atmel Package Drawing Contact: packagedrawings@atmel.com	TITLE 5U-4, 5-ball, 3x3 Array, 0.40mm Pitch, Wafer Level Chip Scale Package (WLCSP) with BSC	GPC GNQ	DRAWING NO. 5U-4	REV. B

13.7 4U-12 — 4-ball WLCSP



PIN ASSIGNMENT MATRIX

	1	2
A	V_{CC}	V_{SS}
B	SCL	SDA

COMMON DIMENSIONS
(Unit of Measure = mm)

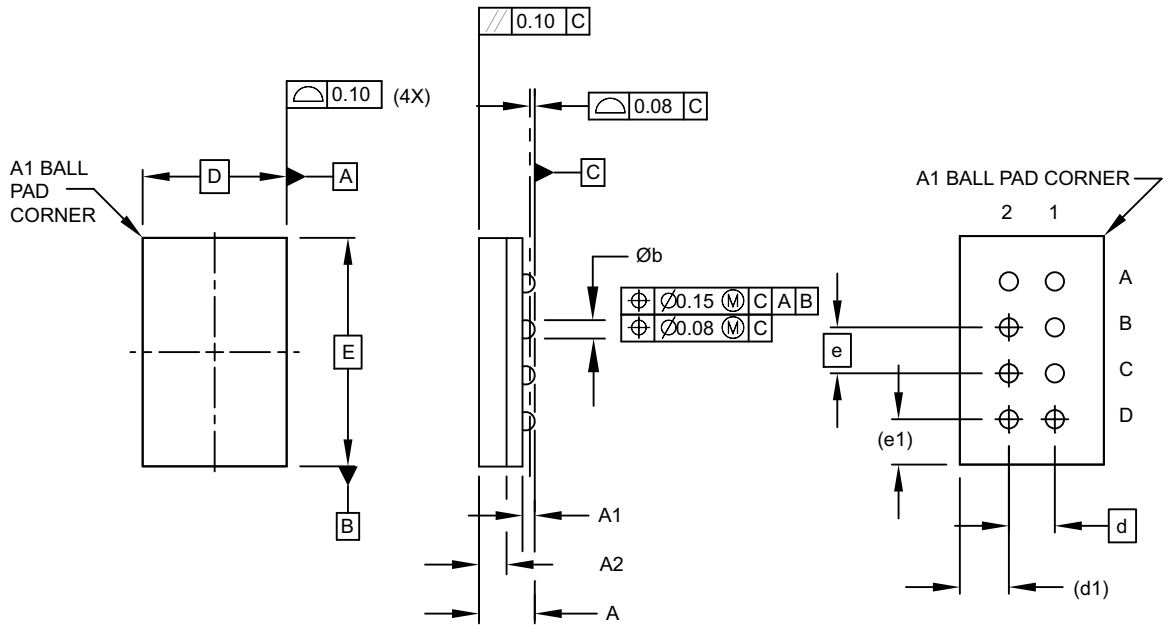
SYMBOL	MIN	TYP	MAX	NOTE
A	0.260	0.295	0.330	
A1	0.080	0.095	0.110	
A2	0.160	0.175	0.190	
A3	0.025 REF			3
D	Contact Atmel for details			
d1	0.400 BSC			
E	Contact Atmel for details			
e1	0.400 BSC			
b	0.170	0.185	0.200	

Note: 1. Dimensions are NOT to scale.
2. Solder ball composition is 95.5Sn-4.0Ag-0.5Cu.
3. Product offered with Back Side Coating (BSC)

5/6/15

Atmel Package Drawing Contact: packagedrawings@atmel.com	**TITLE** 4U-12, 4-ball, 2x2 Array, 0.40mm Pitch Wafer Level Chip Scale Package (WLCSP) with BSC	**GPC** GVF	**DRAWING NO.** 4U-12	**REV.** A

13.8 8U2-1 — 8-ball VFBGA



TOP VIEW SIDE VIEW BOTTOM VIEW

8 SOLDER BALLS

COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	0.81	0.91	1.00	
A1	0.15	0.20	0.25	
A2	0.40	0.45	0.50	
b	0.25	0.30	0.35	
D	2.35 BSC			
E	3.73 BSC			
e	0.75 BSC			
e1	0.74 REF			
d	0.75 BSC			
d1	0.80 REF			

Notes:

1. This drawing is for general
2. Dimension 'b' is measured at the maximum solder ball diameter.
3. Solder ball composition shall be 95.5Sn-4.0Ag-.5Cu.

6/11/13

Atmel Package Drawing Contact: packagedrawings@atmel.com	TITLE 8U2-1, 8-ball, 2.35 x 3.73 mm Body, 0.75 mm pitch, Very Thin, Fine-Pitch Ball Grid Array Package (VFBGA)	GPC GWW	DRAWING NO. 8U2-1	REV. G

14. Revision History

Doc. Rev.	Date	Comments
8850D	05/2015	Added the 4-ball WLCSP, AT24C64D-U2UM0B-T option. Updated the 8S1 package drawing.
8850C	02/2015	Updated the 6-ball and 5-ball WLCSP package outline drawings to reflect offering of product with backside coating.
8850B	12/2014	Added the AT24C64D-MAHM-E product offering. Updated the 8X, 8MA2, 5U-2, and 8U2-1 package outline drawings and the ordering information.
8850A	08/2013	Initial document release.

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